



April 10, 2012

## **Invensas Targets Ultrabooks and Tablet Applications with DIMM-IN-A-PACKAGE Solution Based on xFD Technology**

***Invensas Will Demo xFD Solutions at IDF Beijing and Present at the International Conference on Electronics Packaging in Tokyo***

SAN JOSE, Calif.--(BUSINESS WIRE)-- Invensas Corporation, a leading provider of semiconductor technology solutions and wholly owned subsidiary of Tessera Technologies, Inc. (Nasdaq: TSRA), today introduced its DIMM-IN-A-PACKAGE™ multi-die face-down (xFD)™ technology for thin and light notebooks, also known as Ultrabooks™, and tablet computers.

Invensas' novel solution delivers the memory capacity and performance of a small outline dual in-line memory module (SODIMM) in a miniature, soldered-down, ball grid array (BGA) package. Although the number of dynamic random access memory (DRAM) chips may vary depending upon the architects' need, a DIMM-IN-A-PACKAGE incorporating one typical product, the Quad Face Down (QFD™) package, can replace a single-sided SO-DIMM in a 16 x 16 x 1.0mm form factor, making it ideal for today's ultra-thin electronics.

"Right now, portable electronics roadmaps demand not just evolutionary products to reduce size and increase performance, but revolutionary solutions that provide a radical simplification of the product design and the supply chain," said Simon McElrea, president of Invensas. "The memory challenge goes well beyond providing the required capacity. It's about creating solutions that significantly reduce motherboard size and complexity, while increasing battery size (and hence life), and then dealing with all the heat. DIMM-IN-A-PACKAGE addresses all these issues simultaneously."

Invensas will offer demonstrations of its xFD solutions in booth GE23 at the Intel Developer Forum (IDF) taking place April 11 and 12, 2012 at the China National Convention Center in Beijing. Invensas will present its Ultrabook DIMM-IN-A-PACKAGE solution at the International Conference on Electronics Packaging (ICEP) at Tokyo Big Sight in Tokyo, Japan. Titled "A multi-die DRAM package for solder-down memory in Ultrabook and Tablet PC applications" and coauthored by Dell Inc., the paper will be part of the technical session program taking place in Room B at 10:50 AM on Friday, April 20, 2012.

### **Safe Harbor Statement**

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected, particularly with respect to the features, benefits and characteristics of Invensas' DIMM-IN-A-PACKAGE multi-die face-down (xFD) technology and Invensas' participation at IDF and ICEP, as well as the subject matter of Invensas' presentations at such events. Material factors that may cause results to differ from the statements made include changes to the plans or operations relating to Tessera Technologies, Inc.'s (the "Company") businesses; market or industry conditions; the future expiration of license agreements and the cessation of related royalty income; the failure, inability or refusal of licensees to pay royalties; delays, setbacks or losses relating to the Company's intellectual property or intellectual property litigations, or any invalidation or limitation of key patents; fluctuations in operating results due to the timing of new license agreements and royalties, or due to legal costs; changes in patent laws, regulation or enforcement, or other factors that might affect the Company's ability to protect or realize the value of its intellectual property; the risk of a decline in demand for semiconductor and camera module products; failure by the industry to adopt technologies covered by the Company's patents; the future expiration of the Company's patents; the Company's ability to successfully complete and integrate acquisitions of businesses, including the pending acquisition of Flextronics's camera module business in Zhuhai, China; the risk of loss of, or decreases in production orders from, customers of acquired businesses; financial and regulatory risks associated with the international nature of the Company's businesses; failure of the Company's products to achieve technological feasibility or profitability; failure to successfully commercialize the Company's products; changes in demand for the products of the Company's customers; limited opportunities to license technologies and sell products due to high concentration in the markets for semiconductors and related products and camera modules; the impact of competing technologies on the demand for the Company's technologies and products; failure of the Company's subsidiary, DigitalOptics Corporation, to become a vertically integrated camera module supplier; and the reliance on a limited number of suppliers for the components used in the manufacture of DigitalOptics products. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this media alert. The Company's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended Dec. 31, 2011, include more information about factors that could affect the Company's financial results. The Company assumes no obligation to update information

contained in this press release. Although this press release may remain available on the Company's and Invensas' website or elsewhere, its continued availability does not indicate that the Company is reaffirming or confirming any of the information contained herein.

### **About Invensas Corporation**

Invensas Corporation, a wholly owned subsidiary of Tessera Technologies, Inc. (Nasdaq: [TSRA - News](#)), acquires, develops, and monetizes strategic intellectual property (IP) in areas such as circuitry design, memory modules, 3-D systems, and advanced interconnect technologies, to serve the dynamic mobile, storage and consumer electronics sectors. The group is headquartered in San Jose, California. For information call 1-408-321-6000 or go to [www.invensas.com](http://www.invensas.com).

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